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# N-Channel 120 V (D-S) 175 °C MOSFET

PRODUC	T SUMMARY	
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)
120	0.0048 at V <sub>GS</sub> = 10 V	126 <sup>a</sup>

# TO-220AB G D S Top View

N-Channel MOSFET

### **FEATURES**

- DT-TrenchPower MOSFET
- Maximum 175 °C junction temperature
- 100 % R<sub>g</sub> and UIS tested

# RoHS COMPLIANT

### **APPLICATIONS**

- Power supplies:
  - Uninterruptible power supplies
  - AC/DC switch-mode power supplies
  - Lighting
- Synchronous rectification
- DC/DC converter
- · Motor drive switch
- DC/AC inverter
- Solar micro inverter
- Class D audio amplifier
- Battery management

ABSOLUTE MAXIMUM RATIN	<b>IGS</b> $T_C = 25  ^{\circ}C$ , unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	120	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>.I</sub> = 175 °C)	$T_C = 25  ^{\circ}C$		126 <sup>a</sup>	A
Continuous Diairi Current (1 j = 173 C)	T <sub>C</sub> = 125 °C	I <sub>D</sub>	92 <sup>a</sup>	
Pulsed Drain Current	I <sub>DM</sub>	480	^	
Avalanche Current		I <sub>AR</sub>	75	
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	280	mJ
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	395 <sup>c</sup>	- W
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	- P	3.75	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.4	C/VV

### Notes:

- a. Package limited.
- b. Duty cycle ≤ 1 %.
- c. See SOA curve for voltage derating.
- d. When mounted on 1" square PCB (FR-4 material).

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				•		
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_{D} = 250  \mu\text{A}$	120			V
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μΑ
	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 60 A		0.0048	0.0065	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C			0.0079	Ω
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C			0.0085	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		55		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		8200		pF
Output Capacitance	C <sub>oss</sub>			1230		
Reverse Transfer Capacitance	C <sub>rss</sub>			120		
Total Gate Charge <sup>c</sup>	Qg			86	120	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$		24		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			29		
Gate Resistance	R <sub>g</sub>		1.5	3.0	6.0	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_1 = 0.6 \Omega$		125		ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55		
Fall Time <sup>c</sup>	t <sub>f</sub>			130		
Source-Drain Diode Ratings and Ch	aracteristics -	Γ <sub>C</sub> = 25 °C <sup>b</sup>				
Continuous Current	I <sub>S</sub>				126	A
Pulsed Current	I <sub>SM</sub>				480	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V		1.0	1.5	V
Reverse Recovery Time	t <sub>rr</sub>			70		ns
Peak Reverse Recovery Charge	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, dl/dt = 100 A/μs		5.5		Α
Reverse Recovery Charge	Q <sub>rr</sub>			0.39		μC

### Notes:

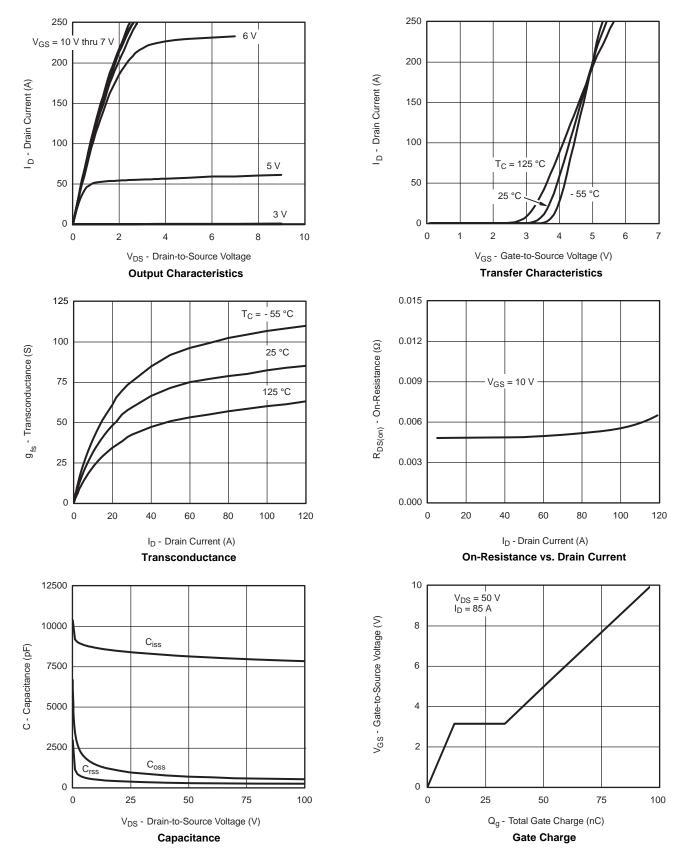
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



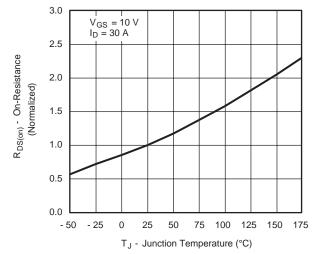


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

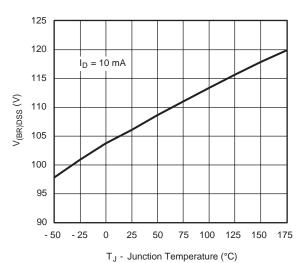




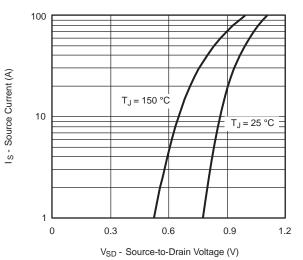
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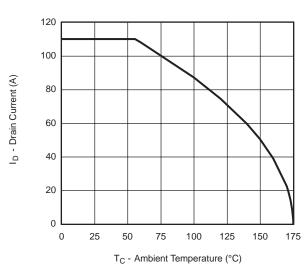
On-Resistance vs. Junction Temperature



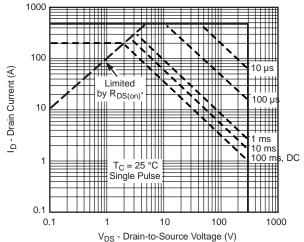
Drain Source Breakdown vs. Junction Temperature



Source-Drain Diode Forward Voltage



Maximum Avalanche and Drain Current vs. Case Temperature

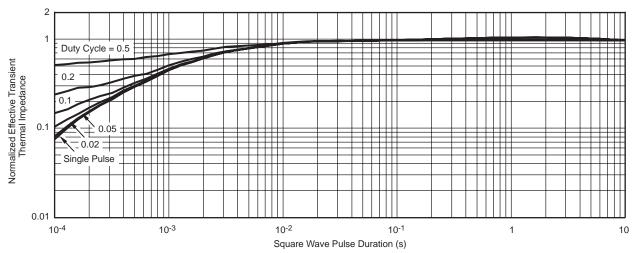


\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area



### **THERMAL RATINGS**



Normalized Thermal Transient Impedance, Junction-to-Case





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